

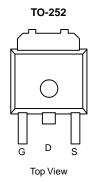
P-Channel 30 V (D-S) MOSFET

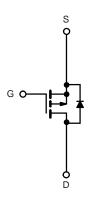
PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a			
- 30	$0.009 \text{ at V}_{GS} = -10 \text{ V}$	± 80			
	0.012 at $V_{GS} = -4.5 \text{ V}$	± 80			

FEATURES

• Compliant to RoHS Directive 2002/95/EC







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)							
Parameter	Symbol	Limit	Unit				
Gate-Source Voltage	V_{GS}	± 20	V				
Continuous Proin Current /T = 175 °C)	T _C = 25 °C		- 80 ^a	Δ.			
Continuous Drain Current (T _J = 175 °C)	T _C = 125 °C	Ι _D	- 65				
Pulsed Drain Current	I _{DM}	- 240	Α				
Avalanche Current	I _{AR}	- 60					
Repetitive Avalanche Energy ^b	L = 0.1 mH	E _{AR}	180	mJ			
Danier Biasinstina	T _C = 25 °C (TO-220AB and TO-263)	Б	187 ^d	W			
Power Dissipation	T _A = 25 °C (TO-263) ^c	P_{D}	3.75				
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount (TO-263) ^c	В	40			
	Free Air (TO-220AB)	R _{thJA}	62.5	°C/W		
Junction-to-Case		R _{th.IC}	0.8			

Notes:

- a. Package limited.
- b. Duty cycle \leq 1 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. See SOA curve for voltage derating.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.



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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Orain-Source Breakdown Voltage V _{DS}		$V_{GS} = 0 \text{ V, } I_D = -250 \mu\text{A}$	- 30			\/	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = - 30 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 125 °C			- 50	- 50 μA - 250	
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 175 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 120			Α	
		V _{GS} = - 10 V, I _D = - 30 A		0.009			
Drain-Source On-State Resistance ^a	ь	V _{GS} = - 10 V, I _D = - 30 A, T _J = 125 °C			0.011		
Diain-Source On-State Resistance	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 30 A, T _J = 175 °C			0.013	Ω	
		V _{GS} = - 4.5 V, I _D = - 20 A		0.008	0.009		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 75 A	20			S	
Dynamic ^b							
Input Capacitance	C _{iss}			9000		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = -25 \text{ V}, f = 1 \text{ MHz}$		1565			
Reversen Transfer Capacitance	C _{rss}			715			
Total Gate Charge ^c	Q_g			160	240		
Gate-Source Charge ^c	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 75 A		32		nC	
Gate-Drain Charge ^c	Q _{gd}			30		1	
Turn-On Delay Time ^c	t _{d(on)}			25	40		
Rise Time ^c	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 0.2 \Omega$		225	360	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong -75 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 2.5 \Omega$		150	240		
Fall Time ^c	t _f			210	340	1	
Source-Drain Diode Ratings and Cha	racteristics ^b	(T _C = 25 °C)					
Continuous Current	I _S				- 80	٨	
Pulsed Current	I _{SM}				- 240	Α	
Forward Voltage ^a	V_{SD}	I _F = -75 A, V _{GS} = 0 V		- 1.2	- 1.5	V	
Reverse Recovery Time	t _{rr}			55	100	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 75 A, dl/dt = 100 A/μs		2.5	5	Α	
Reverse Recovery Charge	Q _{rr}			0.07	0.25	μC	

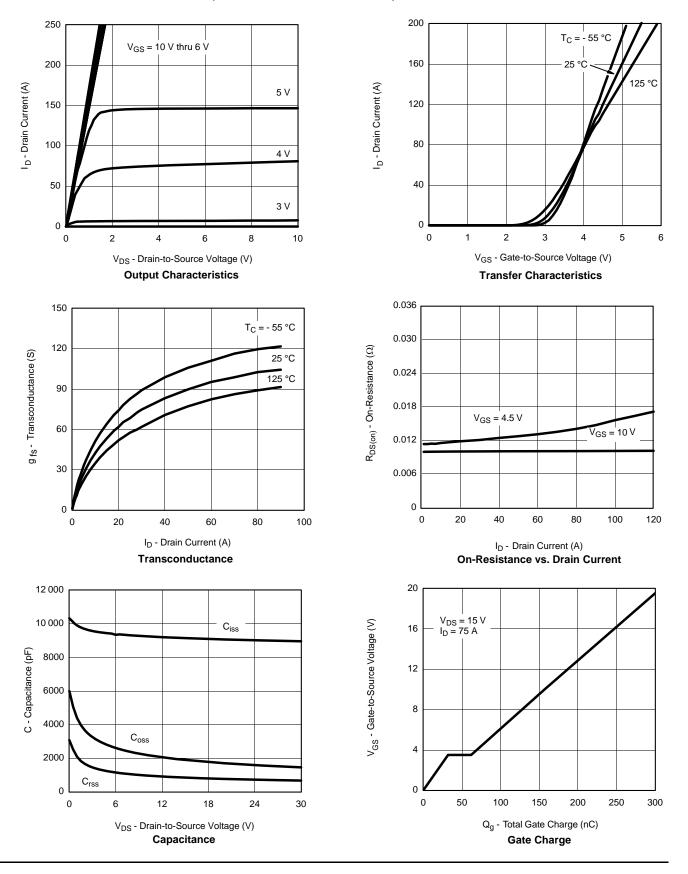
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

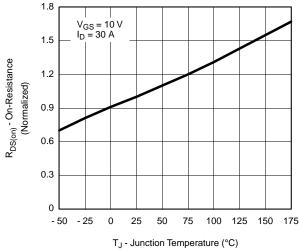


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

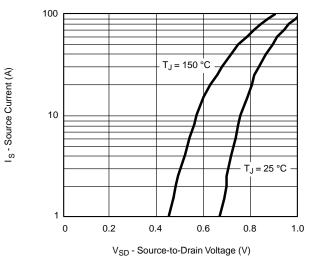




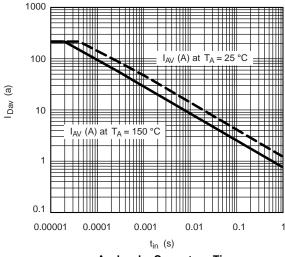
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



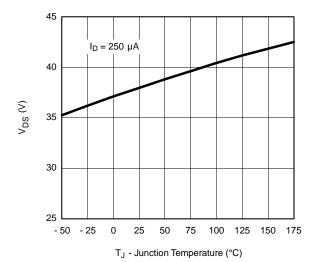
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



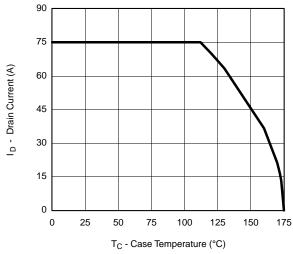
Avalanche Current vs. Time

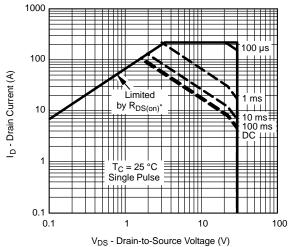


Drain Source Breakdown vs. Junction Temperature

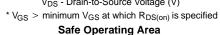


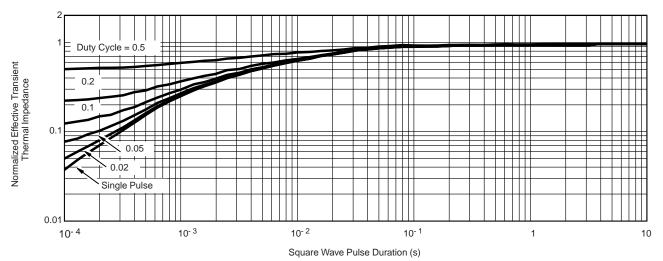
THERMAL RATINGS





Maximum Avalanche and Drain Current vs. Case Temperature



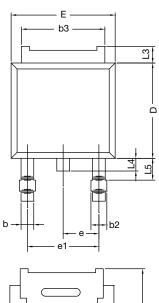


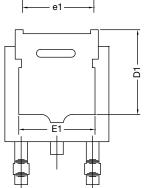
Normalized Thermal Transient Impedance, Junction-to-Case

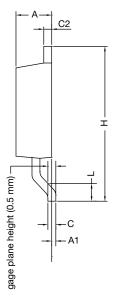
5



TO-252AA CASE OUTLINE







	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28 BSC		0.090 BSC		
e1	4.56	BSC	0.180	BSC	
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M, 24-Dec-12					

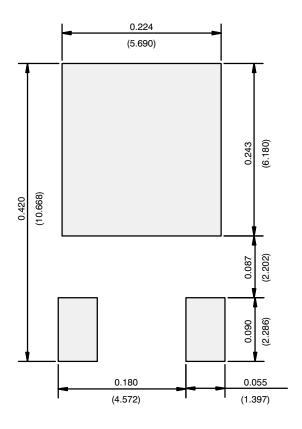
ECN: X12-0247-Rev. M, 24-Dec-1: DWG: 5347

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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